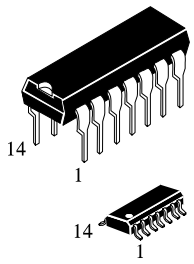
IN74HC393A

Dual 4-Stage Binary Ripple Counter
High-Performance Silicon-Gate CMOS



ORDERING INFORMATION
IN74HC393AN Plastic
IN74HC393AD SOIC
T_A = -55° to 125° C for all packages

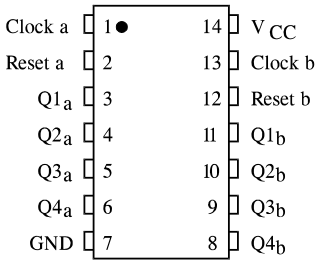
The IN74HC393A is identical in pinout to the LS/ALS393. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LS/ALSTTL outputs.

This device consists of two independent 4-bit binary ripple counters with parallel outputs from each counter stage. A÷256 counter can be obtained by cascading the two binary counters.

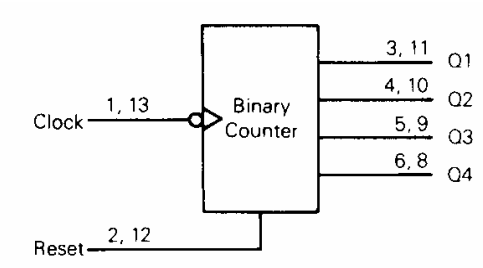
Internal flip-flops are triggered by high-to-low transitions of the clock input. Reset for the counters is asynchronous and active-high. State changes of the Q outputs do not occur simultaneously because of internal ripple delays. Therefore, decoded output signals are subject to decoding spikes and should not be used as clocks or as strobes except when gated with the Clock of the IN74HC393A.

- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices

PIN ASSIGNMENT



LOGIC DIAGRAM



PIN 14 =V_{CC}
PIN 7 = GND

FUNCTION TABLE

Inputs		Outputs
Clock	Reset	
X	H	L
H	L	No Change
L	L	No Change
⌒	L	No Change
⌣	L	Advance to Next State

X = don't care

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	-1.5 to V_{CC} +1.5	V
V_{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Current, per Pin	±25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	±50	mA
P_D	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
Tstg	Storage Temperature	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

*Maximum Ratings are those values beyond which damage to the device may occur.
Functional operation should be restricted to the Recommended Operating Conditions.
+Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C
SOIC Package: : - 7 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)		2.0	6.0	V
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Referenced to GND)		0	V_{CC}	V
T_A	Operating Temperature, All Package Types		-55	+125	°C
t_r, t_f	Input Rise and Fall Time (Figure 1)	V_{CC} =2.0 V V_{CC} =4.5 V V_{CC} =6.0 V	0 0 0	1000 500 400	ns

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{IN} and V_{OUT} should be constrained to the range GND≤(V_{IN} or V_{OUT})≤V_{CC}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V_{CC} V	Guaranteed Limit			Unit
				25 °C to -55°C	≤85 °C	≤125 °C	
V_{IH}	Minimum High-Level Input Voltage	V_{OUT}=0.1 V or V_{CC}-0.1 V $\|I_{OUT}\| \le 20$ μA	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V_{IL}	Maximum Low - Level Input Voltage	V_{OUT}=0.1 V or V_{CC}-0.1 V $\|I_{OUT}\| \le 20$ μA	2.0 4.5 6.0	0.3 0.9 1.2	0.3 0.9 1.2	0.3 0.9 1.2	V
V_{OH}	Minimum High-Level Output Voltage	V_{IN}=V_{IH} or V_{IL} $\|I_{OUT}\| \le 20$ μA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		V_{IN}=V_{IH} or V_{IL} $\|I_{OUT}\| \le 4.0$ mA $\|I_{OUT}\| \le 5.2$ mA	 4.5 6.0	 3.98 5.48	 3.84 5.34	 3.7 5.2	
V_{OL}	Maximum Low-Level Output Voltage	V_{IN}=V_{IH} or V_{IL} $\|I_{OUT}\| \le 20$ μA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		V_{IN}=V_{IH} or V_{IL} $\|I_{OUT}\| \le 4.0$ mA $\|I_{OUT}\| \le 5.2$ mA	 4.5 6.0	 0.26 0.26	 0.33 0.33	 0.4 0.4	
I_{IN}	Maximum Input Leakage Current	V_{IN}=V_{CC} or GND	6.0	±0.1	±1.0	±1.0	μA
I_{CC}	Maximum Quiescent Supply Current (per Package)	V_{IN}=V_{CC} or GND I_{OUT}=0μA	6.0	8.0	80	160	μA

AC ELECTRICAL CHARACTERISTICS (C_L=50pF,Input t_r=t_f=6.0 ns)

Symbol	Parameter	V_{CC} V	Guaranteed Limit			Unit
			25 °C to -55°C	≤85°C	≤125°C	
f_{max}	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 3)	2.0 4.5 6.0	5.4 27 32	4.4 22 26	3.6 18 21	MHz
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Clock to Q1 (Figures 1 and 3)	2.0 4.5 6.0	120 24 20	150 30 26	180 36 31	ns
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Clock to Q2 (Figures 1 and 3)	2.0 4.5 6.0	190 38 32	240 48 41	285 57 48	ns
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Clock to Q3 (Figures 1 and 3)	2.0 4.5 6.0	240 48 41	300 60 51	360 72 61	ns
t_{PLH}, t_{PHL}	Maximum Propagation Delay, Clock to Q4 (Figures 1 and 3)	2.0 4.5 6.0	290 58 49	365 73 62	435 87 74	ns
t_{PHL}	Maximum Propagation Delay, Reset to any Q (Figures 2 and 3)	2.0 4.5 6.0	165 33 28	205 41 35	250 50 43	ns
t_{TLH}, t_{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 3)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C_{IN}	Maximum Input Capacitance	-	10	10	10	pF

C_{PD}	Power Dissipation Capacitance (Per Counter) Used to determine the no-load dynamic power consumption: $P_D=C_{PD}V_{CC}^2f+I_{CC}V_{CC}$	Typical @25°C,V_{CC}=5.0 V 40	pF

TIMING REQUIREMENTS(C_L=50pF,Input t_r=t_f=6.0 ns)

Symbol	Parameter	V_{CC} V	Guaranteed Limit			Unit
			25 °C to-55°C	≤85°C	≤125°C	
t_{rec}	Minimum Recovery Time, Reset Inactive to Clock (Figure 2)	2.0 4.5 6.0	50 10 9	65 13 11	75 15 13	ns
t_w	Minimum Pulse Width, Clock (Figure 1)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
t_w	Minimum Pulse Width, Set (Figure 2)	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
t_r, t_f	Maximum Input Rise and Fall Times (Figure 1)	2.0 4.5 6.0	1000 500 400	1000 500 400	1000 500 400	ns

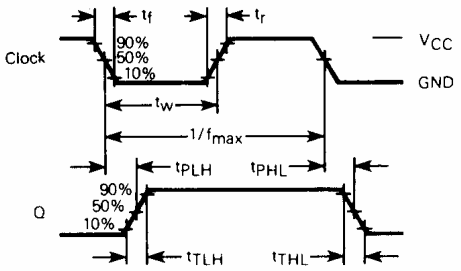


Figure 1. Switching Waveform

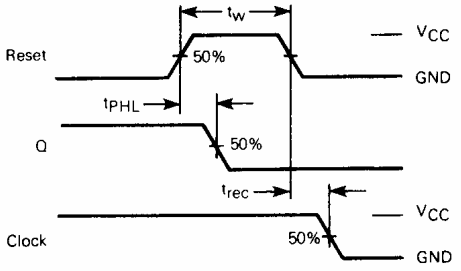


Figure 2. Switching Waveform

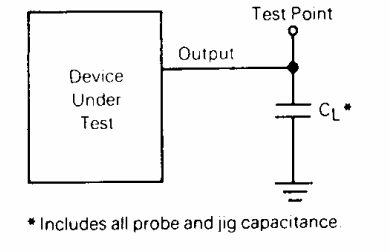
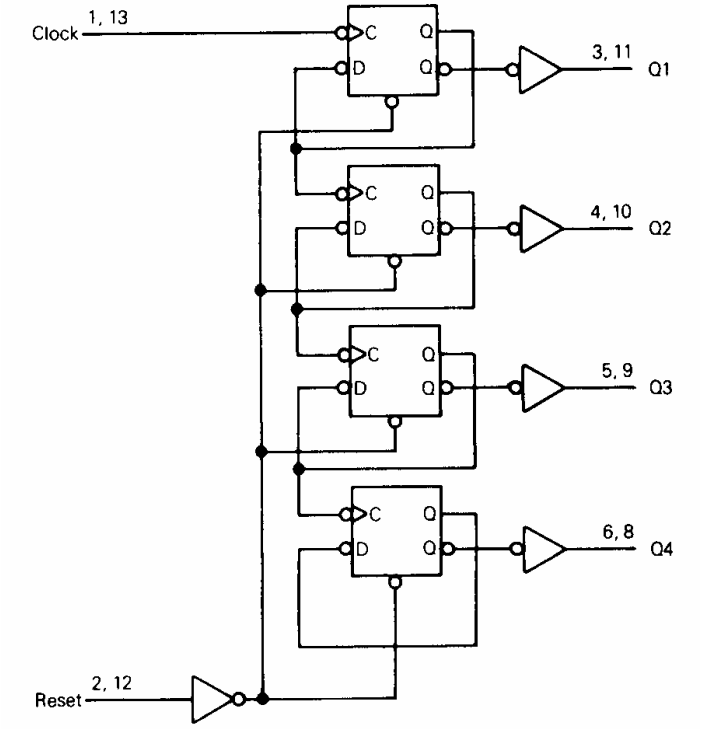
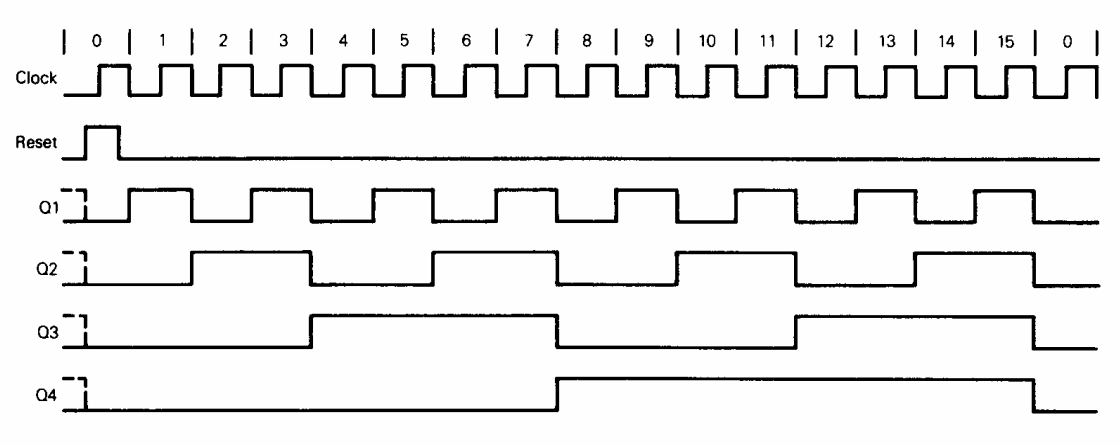


Figure 4.Test Circuit

EXPANDED LOGIC DIAGRAM



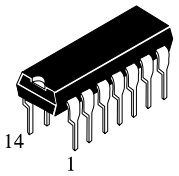
TIMING DIAGRAM

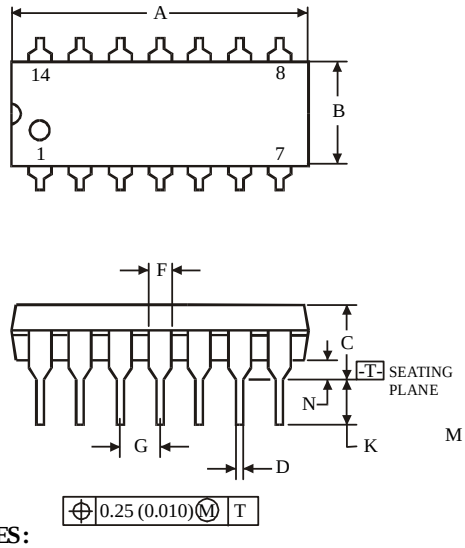


COUNT SEQUENCE

Count	Outputs			
	Q4	Q3	Q2	Q1
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	L	H	L	H
6	L	H	H	L
7	L	H	H	H
8	H	L	L	L
9	H	L	L	H
10	H	L	H	L
11	H	L	H	H
12	H	H	L	L
13	H	H	L	H
14	H	H	H	L
15	H	H	H	H

N SUFFIX PLASTIC DIP
(MS - 001AA)



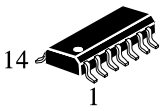


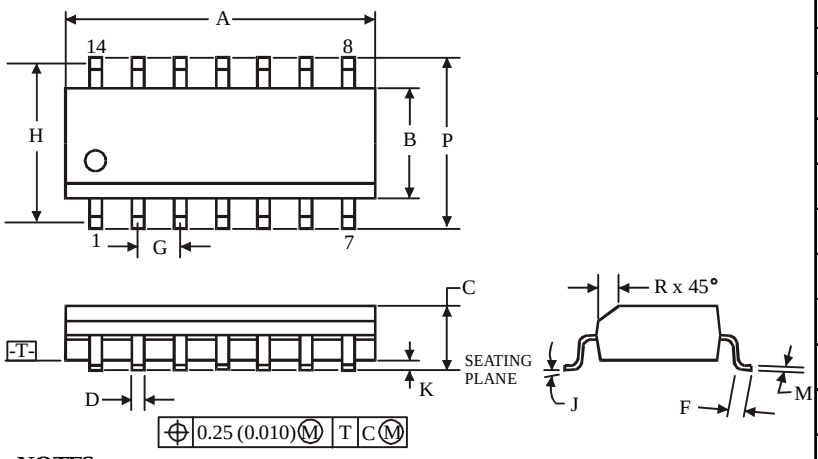
	Dimension, mm	
Symbol	**MIN**	**MAX**
A	18.67	19.69
B	6.1	7.11
C		5.33
D	0.36	0.56
F	1.14	1.78
G	2.54	
H	7.62	
J	0°	10°
K	2.92	3.81
L	7.62	8.26
M	0.2	0.36
N	0.38	

NOTES:

1. Dimensions “A”, “B” do not include mold flash or protrusions.
   Maximum mold flash or protrusions 0.25 mm (0.010) per side.

D SUFFIX SOIC
(MS - 012AB)





	Dimension, mm	
Symbol	**MIN**	**MAX**
A	8.55	8.75
B	3.8	4
C	1.35	1.75
D	0.33	0.51
F	0.4	1.27
G	1.27	
H	5.27	
J	0°	8°
K	0.1	0.25
M	0.19	0.25
P	5.8	6.2
R	0.25	0.5

NOTES:

1. Dimensions A and B do not include mold flash or protrusion.
2. Maximum mold flash or protrusion 0.15 mm (0.006) per side
   for A; for B – 0.25 mm (0.010) per side.